

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t3022emse-1.2#trpbf

(Engineering Calculation)

MSOP-Exposed

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TOTAL MASS (g) : 0.038509

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.003162 | 1000000 | 82110.625 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.013845 | 975000 | 359526.15625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000341 | 24000 | 8855.06835938 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 103.871757507 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000010 | 700 | 259.679382324 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.014200 | 1000000 | 368744.75 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000710 | 1000000 | 18437.8867188 | | |
| | | External Plating Total: | | | | 0.000710 | 1000000 | 18437.8867188 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000086 | 1000000 | 2233.24291992 | | |
| Internal Plating Total: | | | | 0.000086 | 1000000 | 2233.24291992 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000966 | 750000 | 25085.0292969 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000322 | 250000 | 8361.67675781 | | |
| Die Attach Total: | | | | 0.001288 | 1000000 | 33446.7070312 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.002439 | 130000 | 63335.8046875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.015571 | 830000 | 404346.78125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000657 | 35000 | 17060.9375 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000094 | 5000 | 2440.98657227 | | |
| | | Encapsulation Total: | | | | 0.018761 | 1000000 | 487184.53125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000302 | 1000000 | 7842.31835938 | | |
| | | | | | TOTAL MASS (g) : | 0.038509 | | |